

Title (en)
Composite high-frequency component

Title (de)
Zusammengestellte Hochfrequenzkomponente

Title (fr)
Élément composite à hautes fréquences

Publication
EP 0785590 A1 19970723 (EN)

Application
EP 97100647 A 19970116

Priority
JP 486496 A 19960116

Abstract (en)
A composite high-frequency component (10) is designed to occupy only a smaller area and a smaller volume when mounted in an apparatus, to be disposed with improved flexibility, and to be able to operate without an impedance matching circuit. The composite high-frequency component (10) includes a multilayer substrate (11), diodes constituting a high-frequency switch component (1), and a circuit base (12). External terminals for connection to a transmitting circuit, a receiving circuit and an antenna, external terminals for control and an external terminal for connection to ground potential are formed on an outer surface of the multilayer substrate (11). Strip lines and capacitors constituting the high-frequency switch (1) and strip lines and capacitors constituting a low-pass filter circuit (2) are formed in the multilayer substrate (11). <IMAGE>

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H01P 1/15; H01P 1/203

IPC 8 full level
H01F 27/00 (2006.01); **H01P 1/15** (2006.01); **H01P 1/203** (2006.01); **H03H 7/01** (2006.01); **H04B 1/44** (2006.01)

CPC (source: EP KR)
H01P 1/15 (2013.01 - EP); **H01P 1/2039** (2013.01 - EP); **H01Q 13/26** (2013.01 - KR)

Citation (applicant)
• JP H06197042 A 19940715 - MURATA MANUFACTURING CO
• JP H06197043 A 19940715 - MURATA MANUFACTURING CO
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Citation (search report)
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• [A] GB 2289574 A 19951122 - MURATA MANUFACTURING CO [JP]
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